

APPENDIX

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Please amend claims 11 and 12 as follows:

11. (Amended) A method for manufacturing a printed circuit board according to claim [6] 10, comprising, after the step (b), a step of applying a pressure to the upper surfaces of the plurality of capacitors in the cavity to align the upper surfaces of the capacitors to the same heights with each other.

12. A method for manufacturing a printed circuit board according to claim [6] 10, comprising, after the step (c), -a step of forming penetrating openings in the resin layer to form through holes.